

Applicant(s): NAITO et al.

Atty. Dkt.: 01-235

Serial No.: Unknown

Group Art Unit:

Filed: Concurrently herewith

Examiner:

Title: MANUFACTURING METHOD OF

SILICON CARBIDE SINGLE

**CRYSTALS** 

**Assistant Commissioner for Patents** 

Date: December 10, 2001

Washington, D.C. 20231

## INFORMATION DISCLOSURE STATEMENT

Sir:

Pursuant to 37 C.F.R. §1.56, the reference(s) listed on the attached Form PTO-1449 is/are being submitted for consideration by the Examiner without any admission that it/they constitute(s) statutory prior art, or without any admission that it/they contain(s) subject matter that anticipates the invention or renders the invention obvious to a person of ordinary skill in the art.

The Examiner is requested to initial the attached PTO Form-1449 and to return a copy of same to the undersigned attorney as proof that the listed reference(s) has/have been considered and made of record.

Respectfully submitted,

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## **IDS**

[JP·A·2000·34198]

An object is to provide a high productive manufacturing method of a large scale SiC single crystal which is at high purity and high quality, in such a way that crystal boundary, micro-pipe and the like are very few.

A  $\theta$ -SiC polycrystalline layer 2 is formed on a  $\theta$ -SiC single crystal substrate 1 by thermal CVD method to form composite M. The composite M is subjected to thermal treatment at high temperature of 2100 to 2400 °C to recrystallieze the  $\theta$ -SiC polycrystalline layer 2 to form a single crystal. As a result,  $\alpha$ -SiC is grown large to be unified, which is composed of the single crystal and the  $\theta$ -SiC single crystal substrate 1 in which crystal axes are oriented same direction.